

FEATURES

- **Wide Input Voltage Range: 4V to 80V**
- **Low Quiescent Current: 40 μ A**
- **Low Dropout Voltage: 400mV**
- **Output Current: 250mA**
- No Protection Diodes Needed
- Adjustable Output from 1.24V to 60V
- Stable with 3.3 μ F Output Capacitor
- Stable with Aluminum, Tantalum or Ceramic Capacitors
- Reverse-Battery Protection
- No Reverse Current Flow from Output to Input
- Thermal Limiting
- Thermally Enhanced 16-Lead TSSOP and 12-Pin (4mm \times 3mm) DFN Packages

APPLICATIONS

- Low Current High Voltage Regulators
- Regulator for Battery-Powered Systems
- Telecom Applications
- Automotive Applications

DESCRIPTION

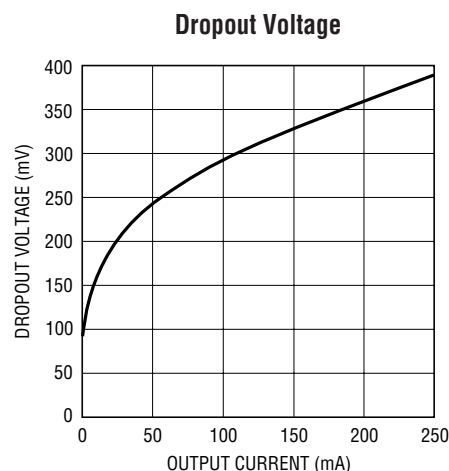
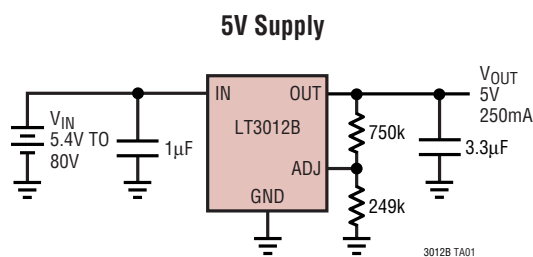
The LT[®]3012B is a high voltage, micropower low dropout linear regulator. The device is capable of supplying 250mA of output current with a dropout voltage of 400mV. Designed for use in battery-powered or high voltage systems, the low quiescent current (40 μ A operating) makes the LT3012B an ideal choice. Quiescent current is also well controlled in dropout.

Other features of the LT3012B include the ability to operate with very small output capacitors. The regulators are stable with only 3.3 μ F on the output while most older devices require between 10 μ F and 100 μ F for stability. Small ceramic capacitors can be used without any need for series resistance (ESR) as is common with other regulators. Internal protection circuitry includes reverse-battery protection, current limiting, thermal limiting and reverse current protection.

The device is available with an adjustable output with a 1.24V reference voltage. The LT3012B regulator is available in the 16-lead TSSOP and 12 pin low profile (0.75mm) (4mm \times 3mm) DFN packages with an exposed pad for enhanced thermal handling capability.

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TYPICAL APPLICATION



3012B TA02

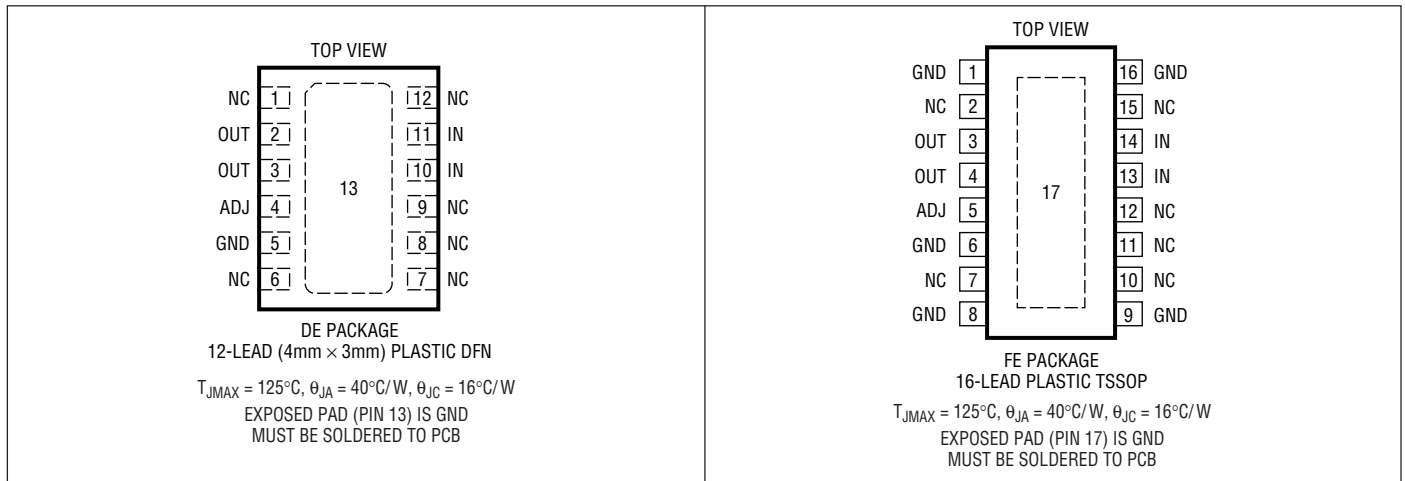
3012bf

LT3012B

ABSOLUTE MAXIMUM RATINGS (Note 1)

IN Pin Voltage	±80V	Storage Temperature Range	
OUT Pin Voltage	±60V	TSSOP Package	–65°C to 150°C
IN to OUT Differential Voltage	±80V	DFN Package	–65°C to 125°C
ADJ Pin Voltage	±7V	Operating Junction Temperature Range	
Output Short-Circuit Duration	Indefinite	(Notes 3, 9, 10)	–40°C to 125°C
		Lead Temperature (Soldering, 10 sec)	300°C

PACKAGE/ORDER INFORMATION



ORDER PART NUMBER	DE PART MARKING	ORDER PART NUMBER	FE PART MARKING
LT3012BEDE	3012B	LT3012BEFE	3012BEFE

Order Options Tape and Reel: Add #TR
 Lead Free: Add #PBF Lead Free Tape and Reel: Add #TRPBF
 Lead Free Part Marking: <http://www.linear.com/leadfree/>

Consult LTC Marketing for parts specified with wider operating temperature ranges.

ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_J = 25^{\circ}C$.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
Minimum Input Voltage	$I_{LOAD} = 250mA$	●	4	4.5	V	
ADJ Pin Voltage (Notes 2, 3)	$V_{IN} = 4V$, $I_{LOAD} = 1mA$ $4.5V < V_{IN} < 80V$, $1mA < I_{LOAD} < 250mA$	●	1.225	1.24	1.255	V
Line Regulation	$\Delta V_{IN} = 4V$ to $80V$, $I_{LOAD} = 1mA$ (Note 2)	●	0.1	5	mV	
Load Regulation (Note 2)	$V_{IN} = 4.5V$, $\Delta I_{LOAD} = 1mA$ to $250mA$ $V_{IN} = 4.5V$, $\Delta I_{LOAD} = 1mA$ to $250mA$	●	7	12	mV	
				25	mV	

ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_J = 25^\circ\text{C}$.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Dropout Voltage $V_{IN} = V_{OUT(NOMINAL)}$ (Notes 4, 5)	$I_{LOAD} = 10\text{mA}$ $I_{LOAD} = 10\text{mA}$	●	160	230 300	mV mV
	$I_{LOAD} = 50\text{mA}$ $I_{LOAD} = 50\text{mA}$	●	250	340 420	mV mV
	$I_{LOAD} = 250\text{mA}$ $I_{LOAD} = 250\text{mA}$	●	400	490 620	mV mV
GND Pin Current $V_{IN} = 4.5\text{V}$ (Notes 4, 6)	$I_{LOAD} = 0\text{mA}$	●	40	100	μA
	$I_{LOAD} = 100\text{mA}$	●	3		mA
	$I_{LOAD} = 250\text{mA}$	●	10	18	mA
Output Voltage Noise	$C_{OUT} = 10\mu\text{F}$, $I_{LOAD} = 250\text{mA}$, BW = 10Hz to 100kHz		100		μV_{RMS}
ADJ Pin Bias Current	(Note 7)		30	100	nA
Ripple Rejection	$V_{IN} = 7\text{V(Avg)}$, $V_{RIPPLE} = 0.5\text{V}_{P-P}$, $f_{RIPPLE} = 120\text{Hz}$, $I_{LOAD} = 250\text{mA}$		65	75	dB
Current Limit	$V_{IN} = 7\text{V}$, $V_{OUT} = 0\text{V}$			400	mA
	$V_{IN} = 4.5\text{V}$, $\Delta V_{OUT} = -0.1\text{V}$ (Note 2)	●	270		mA
Reverse Output Current (Note 8)	$V_{OUT} = 1.24\text{V}$, $V_{IN} < 1.24\text{V}$ (Note 2)		12	25	μA

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: The LT3012B is tested and specified for these conditions with the ADJ pin connected to the OUT pin.

Note 3: Operating conditions are limited by maximum junction temperature. The regulated output voltage specification will not apply for all possible combinations of input voltage and output current. When operating at maximum input voltage, the output current range must be limited. When operating at maximum output current, the input voltage range must be limited.

Note 4: To satisfy requirements for minimum input voltage, the LT3012B is tested and specified for these conditions with an external resistor divider (249k bottom, 549k top) for an output voltage of 4V. The external resistor divider will add a 5 μA DC load on the output.

Note 5: Dropout voltage is the minimum input to output voltage differential needed to maintain regulation at a specified output current. In dropout, the output voltage will be equal to $(V_{IN} - V_{DROPOUT})$.

Note 6: GND pin current is tested with $V_{IN} = 4.5\text{V}$ and a current source load. This means the device is tested while operating close to its dropout region. This is the worst-case GND pin current. The GND pin current will decrease slightly at higher input voltages.

Note 7: ADJ pin bias current flows into the ADJ pin.

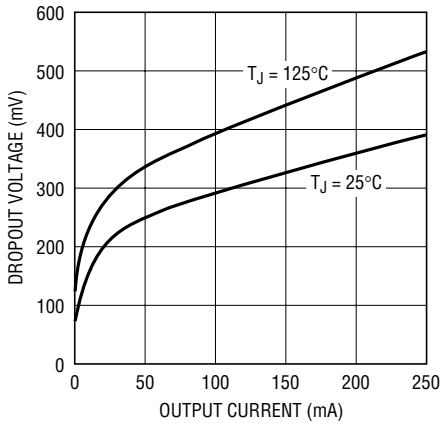
Note 8: Reverse output current is tested with the IN pin grounded and the OUT pin forced to the rated output voltage. This current flows into the OUT pin and out the GND pin.

Note 9: The LT3012BE is guaranteed to meet performance specifications from 0°C to 125°C operating junction temperature. Specifications over the -40°C to 125°C operating junction temperature range are assured by design, characterization and correlation with statistical process controls.

Note 10: This IC includes overtemperature protection that is intended to protect the device during momentary overload conditions. Junction temperature will exceed 125°C when overtemperature protection is active. Continuous operation above the specified maximum operating junction temperature may impair device reliability.

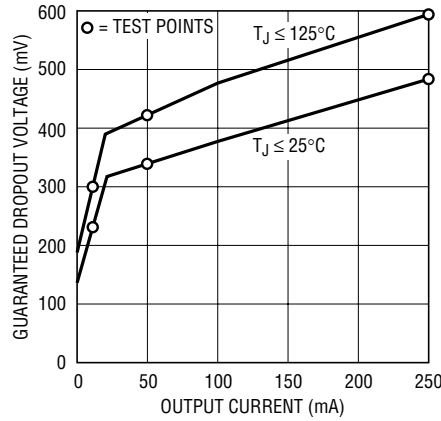
TYPICAL PERFORMANCE CHARACTERISTICS

Typical Dropout Voltage



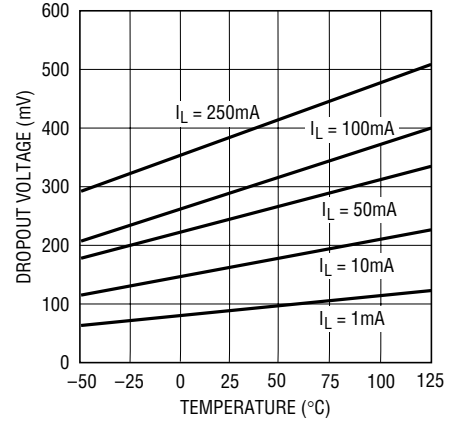
3012B G01

Guaranteed Dropout Voltage



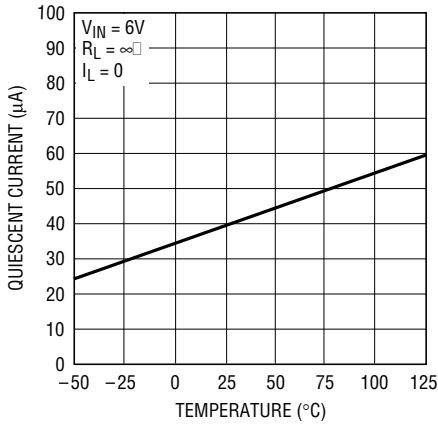
3012B G02

Dropout Voltage



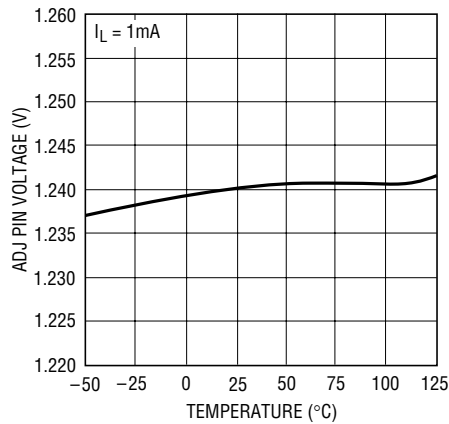
3012B G03

Quiescent Current



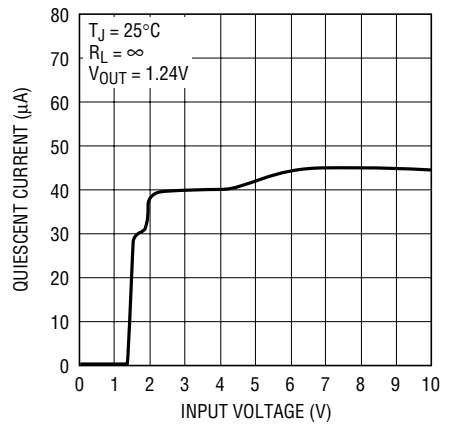
3012B G04

ADJ Pin Voltage



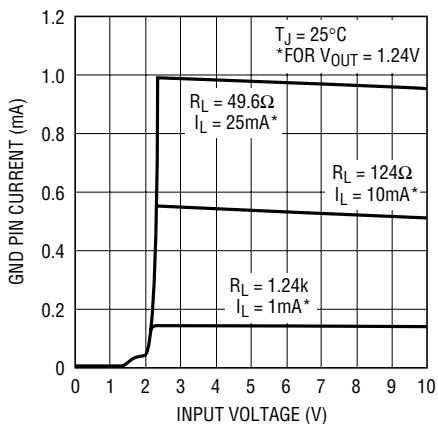
3012B G05

Quiescent Current



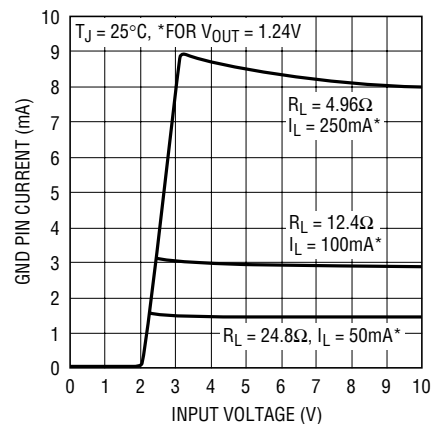
3012B G06

GND Pin Current



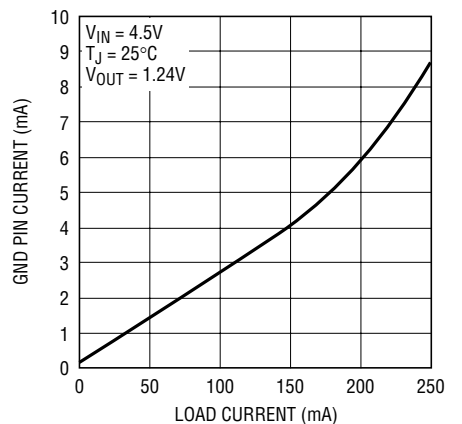
3012B G07

GND Pin Current



3012B G08

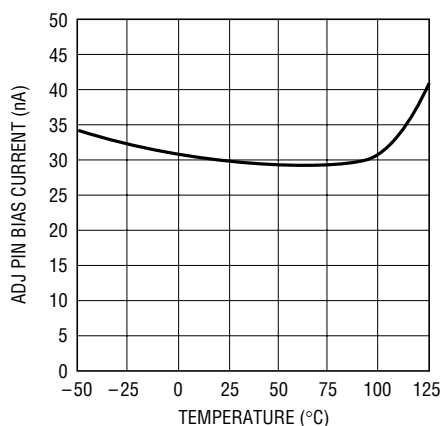
GND Pin Current vs ILOAD



3012B G09

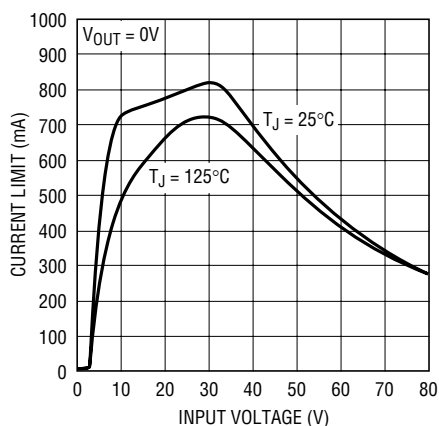
TYPICAL PERFORMANCE CHARACTERISTICS

ADJ Pin Bias Current



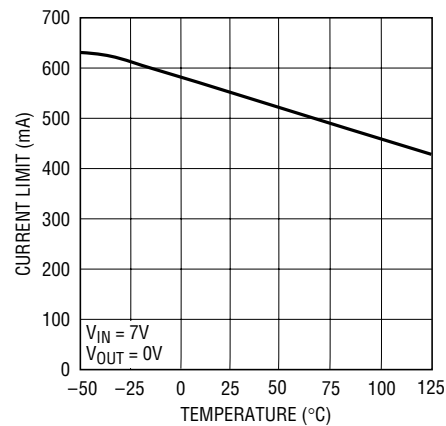
3012B G13

Current Limit



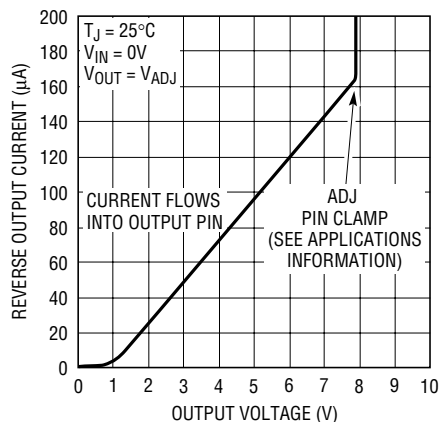
3012B G14

Current Limit



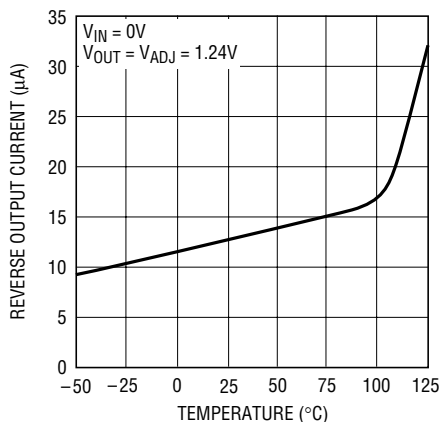
3012B G15

Reverse Output Current



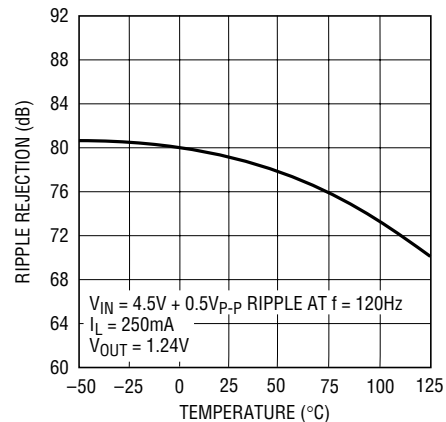
3012B G16

Reverse Output Current



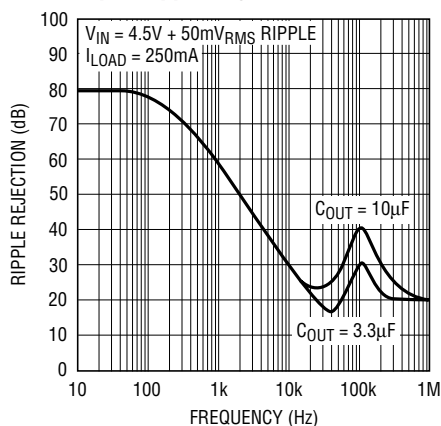
3012B G17

Input Ripple Rejection



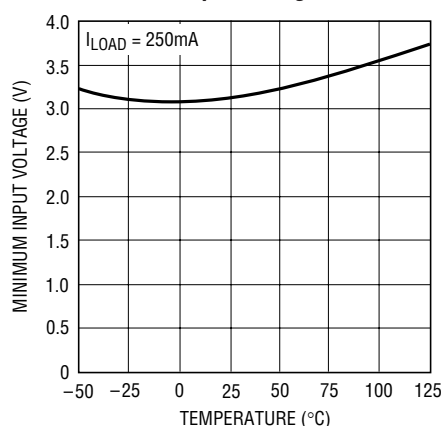
3012B G18

Input Ripple Rejection



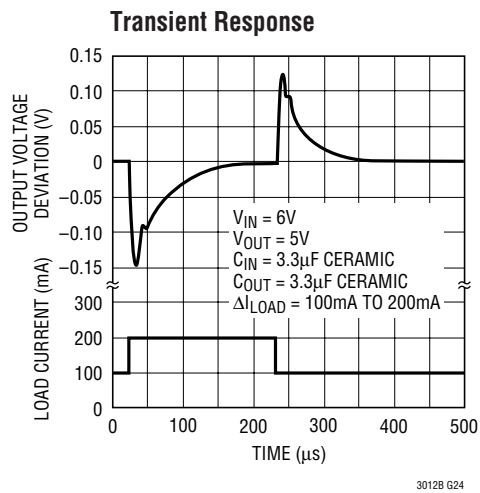
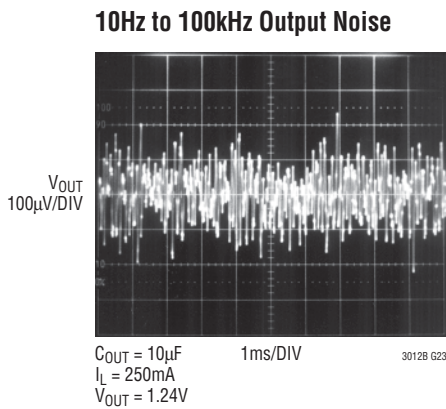
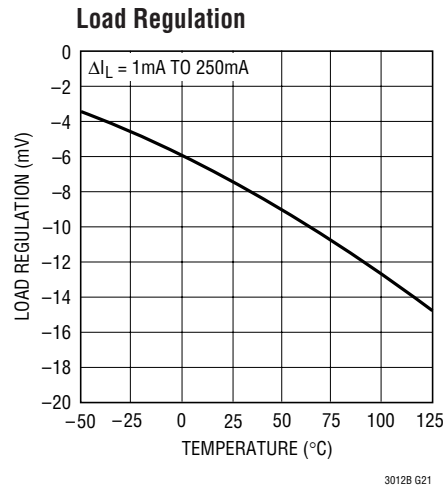
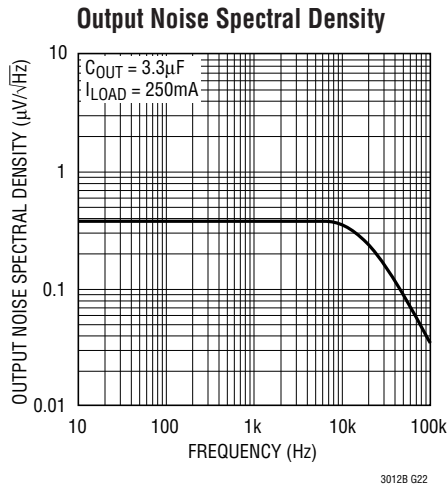
3012B G19

Minimum Input Voltage



3012B G20

TYPICAL PERFORMANCE CHARACTERISTICS



PIN FUNCTIONS (DFN Package)/(TSSOP Package)

OUT (Pins 2, 3)/(Pins 3, 4): Output. The output supplies power to the load. A minimum output capacitor of 3.3 μ F is required to prevent oscillations. Larger output capacitors will be required for applications with large transient loads to limit peak voltage transients. See the Applications Information section for more information on output capacitance and reverse output characteristics.

ADJ (Pin 4)/(Pin 5): Adjust. This is the input to the error amplifier. This pin is internally clamped to ± 7 V. It has a bias current of 30nA which flows into the pin (see curve of ADJ Pin Bias Current vs Temperature in the Typical Performance Characteristics). The ADJ pin voltage is 1.24V referenced to ground, and the output voltage range is 1.24V to 60V.

GND (Pins 5, 13)/(Pins 1, 6, 8, 9, 16, 17): Ground. The exposed backside of the package is an electrical connection for GND. As such, to ensure optimum device operation and thermal performance, the exposed pad must be connected directly to pin 5/pin 6 on the PC board.

IN (Pins 10, 11)/(Pins 13, 14): Input. Power is supplied to the device through the IN pin. A bypass capacitor is required on this pin if the device is more than six inches away from the main input filter capacitor. In general, the output impedance of a battery rises with frequency, so it is advisable to include a bypass capacitor in battery-powered circuits. A bypass capacitor in the range of 1 μ F to 10 μ F is sufficient. The LT3012B is designed to withstand reverse voltages on the IN pin with respect to ground and the OUT pin. In the case of a reversed input, which can happen if a battery is plugged in backwards, the LT3012B will act as if there is a diode in series with its input. There will be no reverse current flow into the LT3012B and no reverse voltage will appear at the load. The device will protect both itself and the load.

NC (Pins 1, 6-9, 12)/(Pins 2, 7, 10-12, 15): No Connect. No Connect pins may be floated, tied to IN or tied to GND.

APPLICATIONS INFORMATION

The LT3012B is a 250mA high voltage low dropout regulator with micropower quiescent current. The device is capable of supplying 250mA at a dropout voltage of 400mV. Operating quiescent current is only 40µA. In addition to the low quiescent current, the LT3012B incorporates several protection features which make it ideal for use in battery-powered systems. The device is protected against both reverse input and reverse output voltages. In battery backup applications where the output can be held up by a backup battery when the input is pulled to ground, the LT3012B acts like it has a diode in series with its output and prevents reverse current flow.

Adjustable Operation

The LT3012B has an output voltage range of 1.24V to 60V. The output voltage is set by the ratio of two external resistors as shown in Figure 1. The device serves the output to maintain the voltage at the adjust pin at 1.24V referenced to ground. The current in R1 is then equal to 1.24V/R1 and the current in R2 is the current in R1 plus the ADJ pin bias current. The ADJ pin bias current, 30nA at 25°C, flows through R2 into the ADJ pin. The output voltage can be calculated using the formula in Figure 1. The value of R1 should be less than 250k to minimize errors in the output voltage caused by the ADJ pin bias current.

The adjustable device is tested and specified with the ADJ pin tied to the OUT pin and a 5µA DC load (unless otherwise specified) for an output voltage of 1.24V. Specifications for output voltages greater than 1.24V will be proportional

to the ratio of the desired output voltage to 1.24V; ($V_{OUT}/1.24V$). For example, load regulation for an output current change of 1mA to 250mA is -7mV typical at $V_{OUT} = 1.24V$. At $V_{OUT} = 12V$, load regulation is:

$$(12V/1.24V) \cdot (-7mV) = -68mV$$

Output Capacitance and Transient Response

The LT3012B is designed to be stable with a wide range of output capacitors. The ESR of the output capacitor affects stability, most notably with small capacitors. A minimum output capacitor of 3.3µF with an ESR of 3Ω or less is recommended to prevent oscillations. The LT3012B is a micropower device and output transient response will be a function of output capacitance. Larger values of output capacitance decrease the peak deviations and provide improved transient response for larger load current changes. Bypass capacitors, used to decouple individual components powered by the LT3012B, will increase the effective output capacitor value.

Extra consideration must be given to the use of ceramic capacitors. Ceramic capacitors are manufactured with a variety of dielectrics, each with different behavior across temperature and applied voltage. The most common dielectrics used are specified with EIA temperature characteristic codes of Z5U, Y5V, X5R and X7R. The Z5U and Y5V dielectrics are good for providing high capacitances in a small package, but they tend to have strong voltage and temperature coefficients as shown in Figures 2 and 3. When used with a 5V regulator, a 16V 10µF Y5V capacitor

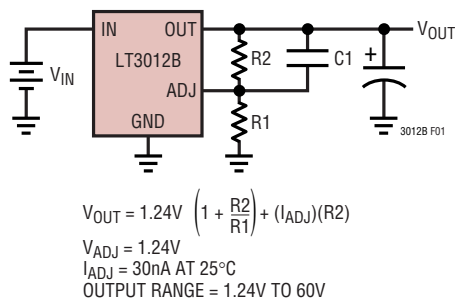


Figure 1. Adjustable Operation

APPLICATIONS INFORMATION

can exhibit an effective value as low as 1 μ F to 2 μ F for the DC bias voltage applied and over the operating temperature range. The X5R and X7R dielectrics result in more stable characteristics and are more suitable for use as the output capacitor. The X7R type has better stability across temperature, while the X5R is less expensive and is available in higher values. Care still must be exercised when using X5R and X7R capacitors; the X5R and X7R codes only specify operating temperature range and maximum capacitance change over temperature. Capacitance change due to DC bias with X5R and X7R capacitors is better than Y5V and Z5U capacitors, but can still be significant enough to drop capacitor values below appropriate levels. Capacitor DC bias characteristics tend to improve as component case size increases, but expected capacitance at operating voltage should be verified.

Voltage and temperature coefficients are not the only sources of problems. Some ceramic capacitors have a piezoelectric response. A piezoelectric device generates voltage across its terminals due to mechanical stress, similar to the way a piezoelectric accelerometer or microphone works. For a ceramic capacitor the stress can be induced by vibrations in the system or thermal transients.

Current Limit and Safe Operating Area Protection

Like many IC power regulators, the LT3012B has safe operating area protection. The safe operating area protection decreases the current limit as the input voltage increases and keeps the power transistor in a safe operat-

ing region. The protection is designed to provide some output current at all values of input voltage up to the device breakdown (see curve of Current Limit vs Input Voltage in the Typical Performance Characteristics).

The LT3012B is limited for operating conditions by maximum junction temperature. While operating at maximum input voltage, the output current range must be limited; when operating at maximum output current, the input voltage range must be limited. Device specifications will not apply for all possible combinations of input voltage and output current. Operating the LT3012B beyond the maximum junction temperature rating may impair the life of the device.

Thermal Considerations

The power handling capability of the device will be limited by the maximum rated junction temperature (125°C). The power dissipated by the device will be made up of two components:

1. Output current multiplied by the input/output voltage differential: $I_{OUT} \cdot (V_{IN} - V_{OUT})$ and,
2. GND pin current multiplied by the input voltage: $I_{GND} \cdot V_{IN}$.

The GND pin current can be found by examining the GND Pin Current curves in the Typical Performance Characteristics. Power dissipation will be equal to the sum of the two components listed above.

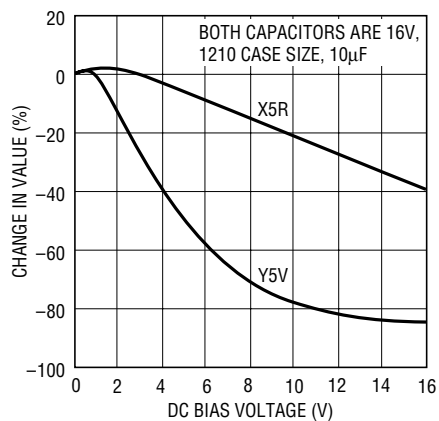


Figure 2. Ceramic Capacitor DC Bias Characteristics

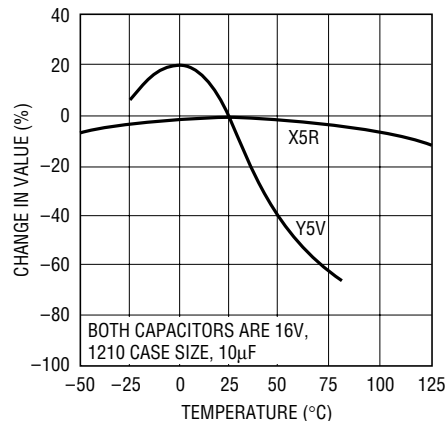


Figure 3. Ceramic Capacitor Temperature Characteristics

APPLICATIONS INFORMATION

The LT3012B has internal thermal limiting designed to protect the device during overload conditions. For continuous normal conditions the maximum junction temperature rating of 125°C must not be exceeded. It is important to give careful consideration to all sources of thermal resistance from junction to ambient. Additional heat sources mounted nearby must also be considered.

For surface mount devices, heat sinking is accomplished by using the heat spreading capabilities of the PC board and its copper traces. Copper board stiffeners and plated through-holes can also be used to spread the heat generated by power devices.

The following tables list thermal resistance for several different board sizes and copper areas. All measurements were taken in still air on 3/32" FR-4 board with one ounce copper.

Table 1. DFN Measured Thermal Resistance

COPPER AREA		BOARD AREA	THERMAL RESISTANCE (JUNCTION-TO-AMBIENT)
TOPSIDE	BACKSIDE		
2500 sq mm	2500 sq mm	2500 sq mm	40°C/W
1000 sq mm	2500 sq mm	2500 sq mm	45°C/W
225 sq mm	2500 sq mm	2500 sq mm	50°C/W
100 sq mm	2500 sq mm	2500 sq mm	62°C/W

Table 2. TSSOP Measured Thermal Resistance

COPPER AREA		BOARD AREA	THERMAL RESISTANCE (JUNCTION-TO-AMBIENT)
TOPSIDE	BACKSIDE		
2500 sq mm	2500 sq mm	2500 sq mm	40°C/W
1000 sq mm	2500 sq mm	2500 sq mm	45°C/W
225 sq mm	2500 sq mm	2500 sq mm	50°C/W
100 sq mm	2500 sq mm	2500 sq mm	62°C/W

The thermal resistance junction-to-case (θ_{JC}), measured at the exposed pad on the back of the die, is 16°C/W.

Continuous operation at large input/output voltage differentials and maximum load current is not practical due to thermal limitations. Transient operation at high input/output differentials is possible. The approximate thermal time constant for a 2500sq mm 3/32" FR-4 board with maximum topside and backside area for one ounce copper is 3 seconds. This time constant will increase as more thermal mass is added (i.e. vias, larger board, and other components).

For an application with transient high power peaks, average power dissipation can be used for junction temperature calculations as long as the pulse period is significantly less than the thermal time constant of the device and board.

Calculating Junction Temperature

Example 1: Given an output voltage of 5V, an input voltage range of 24V to 30V, an output current range of 0mA to 50mA, and a maximum ambient temperature of 50°C, what will the maximum junction temperature be?

The power dissipated by the device will be equal to:

$$I_{OUT(MAX)} \cdot (V_{IN(MAX)} - V_{OUT}) + (I_{GND} \cdot V_{IN(MAX)})$$

where:

$$I_{OUT(MAX)} = 50mA$$

$$V_{IN(MAX)} = 30V$$

$$I_{GND} \text{ at } (I_{OUT} = 50mA, V_{IN} = 30V) = 1mA$$

So:

$$P = 50mA \cdot (30V - 5V) + (1mA \cdot 30V) = 1.28W$$

The thermal resistance will be in the range of 40°C/W to 62°C/W depending on the copper area. So the junction temperature rise above ambient will be approximately equal to:

$$1.31W \cdot 50°C/W = 65.5°C$$

APPLICATIONS INFORMATION

The maximum junction temperature will then be equal to the maximum junction temperature rise above ambient plus the maximum ambient temperature or:

$$T_{JMAX} = 50^{\circ}\text{C} + 65.5^{\circ}\text{C} = 115.5^{\circ}\text{C}$$

Example 2: Given an output voltage of 5V, an input voltage of 48V that rises to 72V for 5ms(max) out of every 100ms, and a 5mA load that steps to 50mA for 50ms out of every 250ms, what is the junction temperature rise above ambient? Using a 500ms period (well under the time constant of the board), power dissipation is as follows:

$$P1(48\text{V in, } 5\text{mA load}) = 5\text{mA} \cdot (48\text{V} - 5\text{V}) \\ + (200\mu\text{A} \cdot 48\text{V}) = 0.23\text{W}$$

$$P2(48\text{V in, } 50\text{mA load}) = 50\text{mA} \cdot (48\text{V} - 5\text{V}) \\ + (1\text{mA} \cdot 48\text{V}) = 2.20\text{W}$$

$$P3(72\text{V in, } 5\text{mA load}) = 5\text{mA} \cdot (72\text{V} - 5\text{V}) \\ + (200\mu\text{A} \cdot 72\text{V}) = 0.35\text{W}$$

$$P4(72\text{V in, } 50\text{mA load}) = 50\text{mA} \cdot (72\text{V} - 5\text{V}) \\ + (1\text{mA} \cdot 72\text{V}) = 3.42\text{W}$$

Operation at the different power levels is as follows:

76% operation at P1, 19% for P2, 4% for P3, and 1% for P4.

$$P_{EFF} = 76\%(0.23\text{W}) + 19\%(2.20\text{W}) + 4\%(0.35\text{W}) \\ + 1\%(3.42\text{W}) = 0.64\text{W}$$

With a thermal resistance in the range of 40°C/W to 62°C/W, this translates to a junction temperature rise above ambient of 26°C to 38°C.

Protection Features

The LT3012B incorporates several protection features which make it ideal for use in battery-powered circuits. In addition to the normal protection features associated with monolithic regulators, such as current limiting and thermal limiting, the device is protected against reverse-input voltages, and reverse voltages from output to input.

Current limit protection and thermal overload protection are intended to protect the device against current overload conditions at the output of the device. For normal operation, the junction temperature should not exceed 125°C.

The input of the device will withstand reverse voltages of 80V. No negative voltage will appear at the output. The device will protect both itself and the load. This provides protection against batteries which can be plugged in backward.

The ADJ pin of the device can be pulled above or below ground by as much as 7V without damaging the device. If the input is left open circuit or grounded, the ADJ pin will act like an open circuit when pulled below ground, and like a large resistor (typically 100k) in series with a diode when pulled above ground. If the input is powered by a voltage source, pulling the ADJ pin below the reference voltage will cause the device to current limit. This will cause the output to go to a unregulated high voltage. Pulling the ADJ pin above the reference voltage will turn off all output current.

APPLICATIONS INFORMATION

In situations where the ADJ pin is connected to a resistor divider that would pull the ADJ pin above its 7V clamp voltage if the output is pulled high, the ADJ pin input current must be limited to less than 5mA. For example, a resistor divider is used to provide a regulated 1.5V output from the 1.24V reference when the output is forced to 60V. The top resistor of the resistor divider must be chosen to limit the current into the ADJ pin to less than 5mA when the ADJ pin is at 7V. The 53V difference between the OUT and ADJ pins divided by the 5mA maximum current into the ADJ pin yields a minimum top resistor value of 10.6k.

In circuits where a backup battery is required, several different input/output conditions can occur. The output voltage may be held up while the input is either pulled to

ground, pulled to some intermediate voltage, or is left open circuit. Current flow back into the output will follow the curve shown in Figure 4. The rise in reverse output current above 7V occurs from the breakdown of the 7V clamp on the ADJ pin. With a resistor divider on the regulator output, this current will be reduced depending on the size of the resistor divider.

When the IN pin of the LT3012B is forced below the OUT pin or the OUT pin is pulled above the IN pin, input current will typically drop to less than 2 μ A. This can happen if the input of the LT3012B is connected to a discharged (low voltage) battery and the output is held up by either a backup battery or a second regulator circuit.

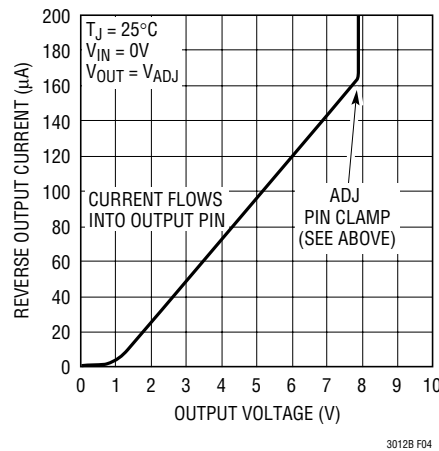
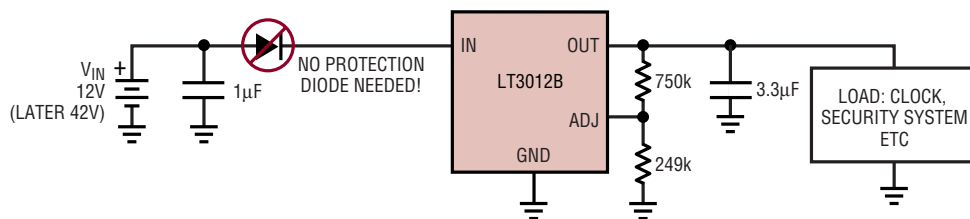


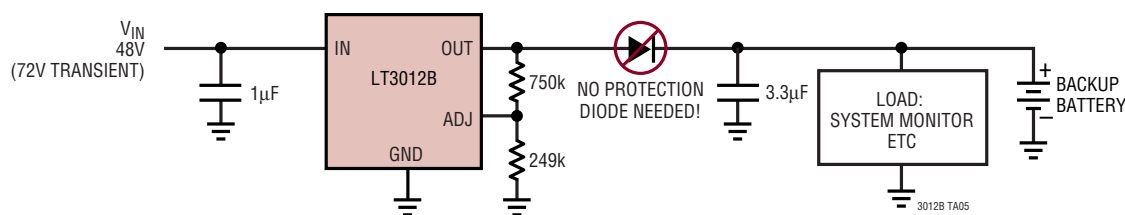
Figure 4. Reverse Output Current

TYPICAL APPLICATIONS

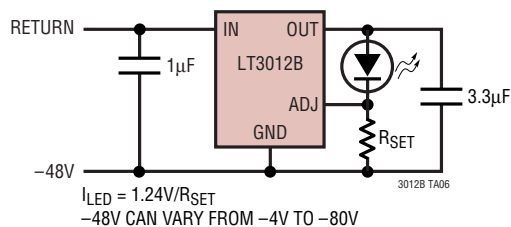
LT3012B Automotive Application



LT3012B Telecom Application

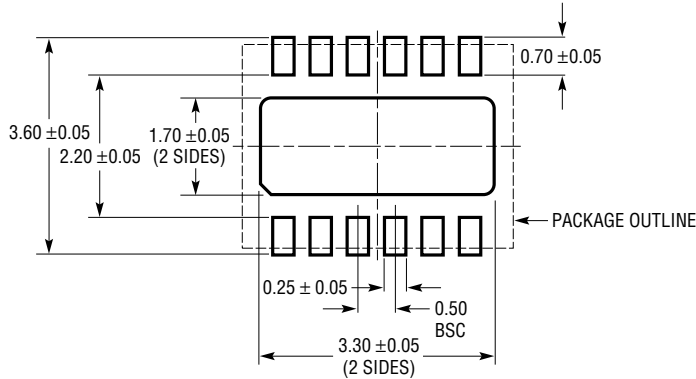


Constant Brightness for Indicator LED over Wide Input Voltage Range

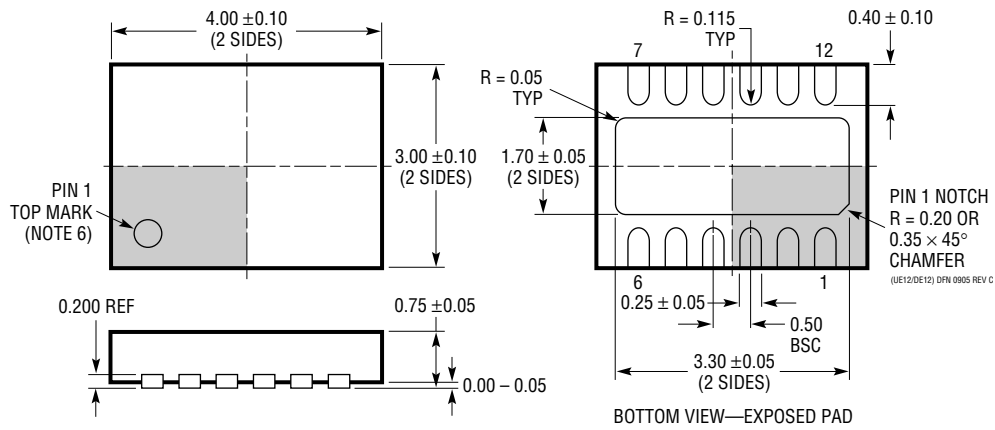


PACKAGE DESCRIPTION

DE/UE Package
12-Lead Plastic DFN (4mm × 3mm)
 (Reference LTC DWG # 05-08-1695 Rev C)



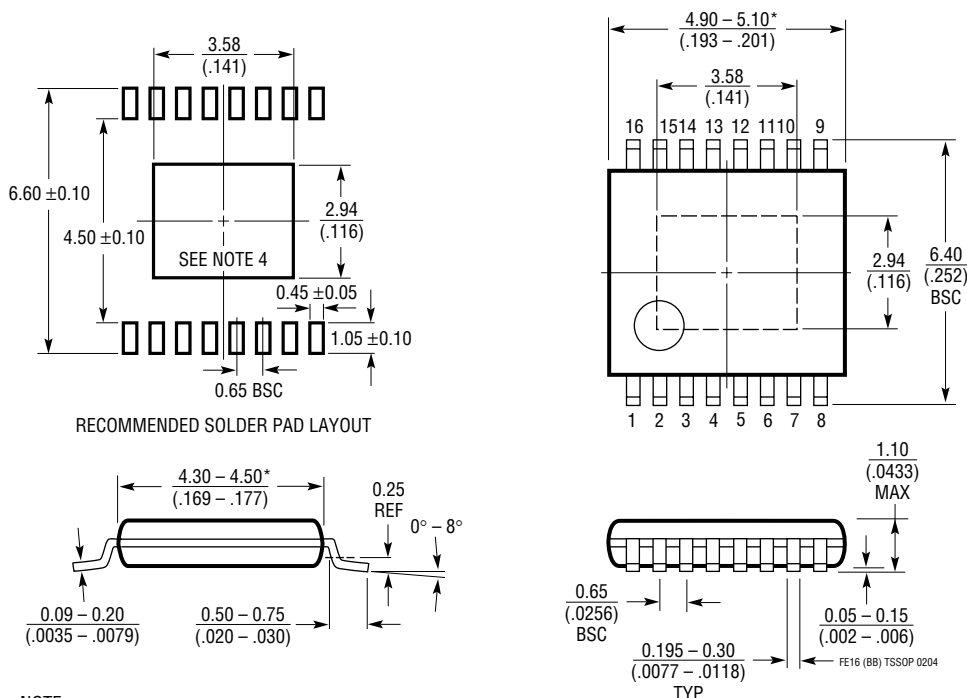
RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS



- NOTE:
1. DRAWING PROPOSED TO BE A VARIATION OF VERSION (WGED) IN JEDEC PACKAGE OUTLINE M0-229
 2. DRAWING NOT TO SCALE
 3. ALL DIMENSIONS ARE IN MILLIMETERS
 4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.15mm ON ANY SIDE
 5. EXPOSED PAD SHALL BE SOLDER PLATED
 6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE

PACKAGE DESCRIPTION

FE Package
16-Lead Plastic TSSOP (4.4mm)
 (Reference LTC DWG # 05-08-1663)
Exposed Pad Variation BB



- NOTE:
1. CONTROLLING DIMENSION: MILLIMETERS
 2. DIMENSIONS ARE IN $\frac{\text{MILLIMETERS}}{\text{INCHES}}$
 3. DRAWING NOT TO SCALE
 4. RECOMMENDED MINIMUM PCB METAL SIZE FOR EXPOSED PAD ATTACHMENT
- *DIMENSIONS DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.150mm (.006") PER SIDE

RELATED PARTS

PART NUMBER	DESCRIPTION	COMMENTS
LT1020	125mA, Micropower Regulator and Comparator	V_{IN} : 4.5V to 36V, $V_{OUT(MIN)}$ = 2.5V, V_{DO} = 0.4V, I_Q = 40 μ A, I_{SD} = 40 μ A, Comparator and Reference, Class B Outputs, S16, PDIP14 Packages
LT1120/LT1120A	125mA, Micropower Regulator and Comparator	V_{IN} : 4.5V to 36V, $V_{OUT(MIN)}$ = 2.5V, V_{DO} = 0.4V, I_Q = 40 μ A, I_{SD} = 10 μ A, Comparator and Reference, Logic Shutdown, Ref Sources and Sinks 2/4mA, S8, N8 Packages
LT1121/ LT1121HV	150mA, Micropower, LDO	V_{IN} : 4.2V to 30/36V, $V_{OUT(MIN)}$ = 3.75V, V_{DO} = 0.42V, I_Q = 30 μ A, I_{SD} = 16 μ A, Reverse Battery Protection, SOT-223, S8, Z Packages
LT1129	700mA, Micropower, LDO	V_{IN} : 4.2V to 30V, $V_{OUT(MIN)}$ = 3.75V, V_{DO} = 0.4V, I_Q = 50 μ A, I_{SD} = 16 μ A, DD, SOT-223, S8, TO220-5, TSSOP20 Packages
LT1676	60V, 440mA (I_{OUT}), 100kHz, High Efficiency Step-Down DC/DC Converter	V_{IN} : 7.4V to 60V, $V_{OUT(MIN)}$ = 1.24V, I_Q = 3.2mA, I_{SD} = 2.5 μ A, S8 Package
LT1761	100mA, Low Noise Micropower, LDO	V_{IN} : 1.8V to 20V, $V_{OUT(MIN)}$ = 1.22V, V_{DO} = 0.3V, I_Q = 20 μ A, I_{SD} = <1 μ A, Low Noise < 20 μ V _{RMS} , Stable with 1 μ F Ceramic Capacitors, ThinSOT Package
LT1762	150mA, Low Noise Micropower, LDO	V_{IN} : 1.8V to 20V, $V_{OUT(MIN)}$ = 1.22V, V_{DO} = 0.3V, I_Q = 25 μ A, I_{SD} = <1 μ A, Low Noise < 20 μ V _{RMS} , MS8 Package
LT1763	500mA, Low Noise Micropower, LDO	V_{IN} : 1.8V to 20V, $V_{OUT(MIN)}$ = 1.22V, V_{DO} = 0.3V, I_Q = 30 μ A, I_{SD} = <1 μ A, Low Noise < 20 μ V _{RMS} , S8 Package
LT1764/LT1764A	3A, Low Noise, Fast Transient Response, LDO	V_{IN} : 2.7V to 20V, $V_{OUT(MIN)}$ = 1.21V, V_{DO} = 0.34V, I_Q = 1mA, I_{SD} = <1 μ A, Low Noise < 40 μ V _{RMS} , "A" Version Stable with Ceramic Capacitors, DD, TO220-5 Packages
LT1766	60V, 1.2A (I_{OUT}), 200kHz, High Efficiency Step-Down DC/DC Converter	V_{IN} : 5.5V to 60V, $V_{OUT(MIN)}$ = 1.2V, I_Q = 2.5mA, I_{SD} = 25 μ A, TSSOP16/E Package
LT1776	40V, 550mA (I_{OUT}), 200kHz, High Efficiency Step-Down DC/DC Converter	V_{IN} : 7.4V to 40V, $V_{OUT(MIN)}$ = 1.24V, I_Q = 3.2mA, I_{SD} = 30 μ A, N8, S8 Packages
LT1934/ LT1934-1	300mA/60mA, (I_{OUT}), Constant Off-Time, High Efficiency Step-Down DC/DC Converter	90% Efficiency, V_{IN} : 3.2V to 34V, $V_{OUT(MIN)}$ = 1.25V, I_Q = 14 μ A, I_{SD} = <1 μ A, ThinSOT Package
LT1956	60V, 1.2A (I_{OUT}), 500kHz, High Efficiency Step-Down DC/DC Converter	V_{IN} : 5.5V to 60V, $V_{OUT(MIN)}$ = 1.2V, I_Q = 2.5mA, I_{SD} = 25 μ A, TSSOP16/E Package
LT1962	300mA, Low Noise Micropower, LDO	V_{IN} : 1.8V to 20V, $V_{OUT(MIN)}$ = 1.22V, V_{DO} = 0.27V, I_Q = 30 μ A, I_{SD} = <1 μ A, Low Noise < 20 μ V _{RMS} , MS8 Package
LT1963/LT1963A	1.5A, Low Noise, Fast Transient Response, LDO	V_{IN} : 2.1V to 20V, $V_{OUT(MIN)}$ = 1.21V, V_{DO} = 0.34V, I_Q = 1mA, I_{SD} = <1 μ A, Low Noise < 40 μ V _{RMS} , "A" Version Stable with Ceramic Capacitors, DD, TO220-5, SOT-223, S8 Packages
LT1964	200mA, Low Noise Micropower, Negative LDO	V_{IN} : -1.9V to -20V, $V_{OUT(MIN)}$ = -1.21V, V_{DO} = 0.34V, I_Q = 30 μ A, I_{SD} = 3 μ A, Low Noise < 30 μ V _{RMS} , Stable with Ceramic Capacitors, ThinSOT Package
LT3010	100mA, 3V to 80V, Low Noise Micropower LDO	V_{IN} : 3V to 8V, $V_{OUT(MIN)}$ = 1.275V, V_{DO} = 0.3V, I_Q = 30 μ A, I_{SD} = 1 μ A, Low Noise < 100 μ V _{RMS} , MS8E Package